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October 2015

FDMA86251

Single N-Channel PowerTrench® MOSFET

150 V, 2.4 A, 175 mΩ

Features

- Max $r_{DS(on)}$ = 175 m Ω at V_{GS} = 10 V, I_D = 2.4 A
- Max $r_{DS(on)}$ = 237 m Ω at V_{GS} = 6 V, I_D = 2.0 A
- Low Profile 0.8 mm maximum in the new package MicroFET 2x2 mm
- Free from halogenated compounds and antimony oxides
- RoHS Compliant

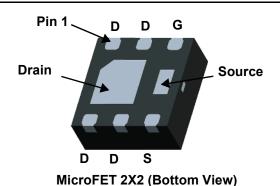


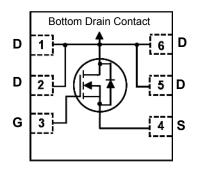
General Description

This device has been designed to provide maximum efficiency and thermal performance for synchronous buck converters. The low rDS(on) and gate charge provide excellent switching performance.

Applications

- DC DC Primary Switch
- Load Switch





MOSFET Maximum Ratings T_A = 25 °C unless otherwise noted.

Symbol	Paran	neter		Ratings	Units
V _{DS}	Drain to Source Voltage			150	V
V _{GS}	Gate to Source Voltage			±20	V
I _D	Drain Curre -Continuous	T _A = 25 °C	(Note 1a)	2.4	
	-Pulsed		(Note 4)	12	Α
E _{AS}	Single Pulse Avalanche Energy		(Note 3)	13	mJ
P_{D}	Power Dissipation	T _A = 25 °C	(Note 1a)	2.4	W
	Power Dissipation	T _A = 25 °C	(Note 1b)	0.9	VV
T _J , T _{STG}	Operating and Storage Junction Temper	rature Range		-55 to +150	°C

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	52	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1b)	145	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
251	FDMA86251	MicroFET 2X2	7 "	8 mm	3000 units

Electrical Characteristics $T_J = 25$ °C unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Chara	cteristics					
BV_{DSS}	Drain to Source Breakdown Voltage	I _D = 250 μA, V _{GS} = 0 V	150			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25 °C		108		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 120 V, V _{GS} = 0 V			1	μΑ
I_{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			100	nA

On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	2.0	2.8	4.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I _D = 250 μA, referenced to 25 °C		-9		mV/°C
	Static Drain to Source On Resistance	V _{GS} = 10 V, I _D = 2.4 A		148	175	
rock)		$V_{GS} = 6 \text{ V}, I_D = 2.0 \text{ A}$		175	237	mΩ
r _{DS(on)} Static	Static Brain to Gource On Resistance	V_{GS} = 10 V, I_{D} = 2.4 A, T_{J} = 125 °C		272	333	11152
g _{FS}	Forward Transconductance	$V_{DD} = 5 \text{ V}, I_{D} = 2.4 \text{ A}$		4.7		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V 75.V.V 0.V		259	363	pF
Coss	Output Capacitance	V _{DS} = 75 V, V _{GS} = 0 V, f = 1 MHz		24	34	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1 1/11/12		1.5	2.4	pF
R_g	Gate Resistance		0.1	1.5	3.0	Ω

Switching Characteristics

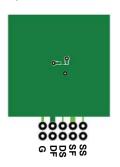
t _{d(on)}	Turn-On Delay Time	.,,	5.9	12	ns
t _r	Rise Time	V_{DD} = 75V, I_D = 2.4 A, V_{GS} = 10 V, R_{GEN} = 6 Ω	1.7	10	ns
t _{d(off)}	Turn-Off Delay Time	V _{GS} = 10 V, R _{GEN} = 012	10	20	ns
t _f	Fall Time		2.3	10	ns
$Q_{g(TOT)}$	Total Gate Charge	V _{GS} = 0 V to 10 V	4.1	5.8	nC
$Q_{g(TOT)}$	Total Gate Charge	$V_{GS} = 0 \text{ V to 6 V} V_{DD} = 75 \text{ V},$	2.7	3.8	nC
Q _{gs}	Gate to Source Charge	I _D = 2.4 A	1.2		nC
Q_{gd}	Gate to Drain "Miller" Charge		1.0		nC

Drain-Source Diode Characteristics

V_{SD}	Source to Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_S = 2.4 \text{ A}$ (Note 2)		0.8	1.2	V
t _{rr}	Reverse Recovery Time	L = 2.4 A di/dt = 100 A/vs		49	79	ns
Q _{rr}	Reverse Recovery Charge	I _F = 2.4 A, di/dt = 100 A/μs		38	61	nC

Notes

^{1:} R_{0,D,A} is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{0,UC} is guaranteed by design while R_{0,UA} is determined by the user's board design.



a. 52 °C/W when mounted on a 1 in² pad of 2 oz copper.



b. 145 °C/W when mounted on a minimum pad of 2 oz copper.

- 2: Pulse Test: Pulse Width < 300 μ s, Duty cycle < 2.0%.
- 3: E_{AS} of 13 mJ is based on starting $T_J = 25$ °C, L = 3 mH, $I_{AS} = 3$ A, $V_{DD} = 150$ V, $V_{GS} = 10$ V. 100% tested at L = 0.3 mH, $I_{AS} = 8$ A.
- 4: Pulsed Id please refer to Fig 9 SOA graph for more details.

Typical Characteristics T_J = 25 °C unless otherwise noted.

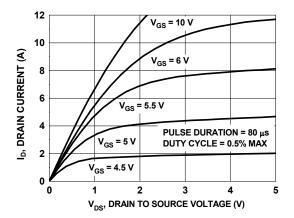


Figure 1. On Region Characteristics

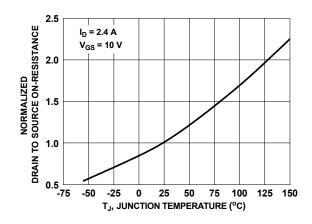


Figure 3. Normalized On Resistance vs. Junction Temperature

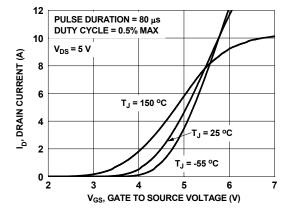


Figure 5. Transfer Characteristics

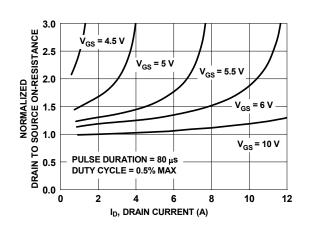


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

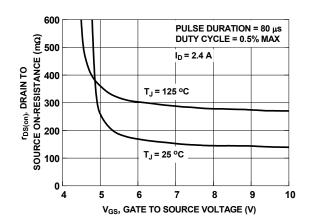


Figure 4. On-Resistance vs. Gate to Source Voltage

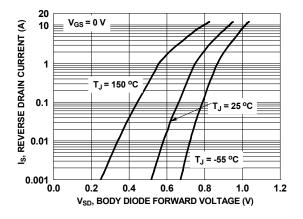


Figure 6. Source to Drain Diode Forward Voltage vs. Source Current

Typical Characteristics T_J = 25 °C unless otherwise noted.

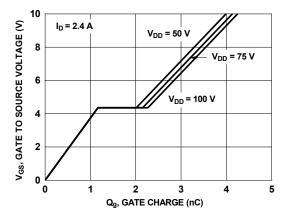


Figure 7. Gate Charge Characteristics

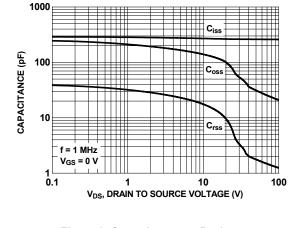


Figure 8. Capacitance vs. Drain to Source Voltage

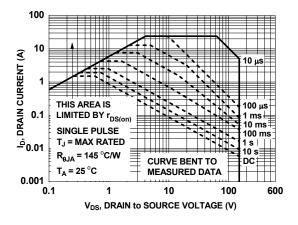


Figure 9. Forward Bias Safe Operating Area

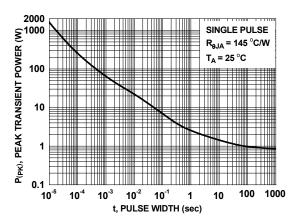


Figure 10. Single Pulse Maximum Power Dissipation

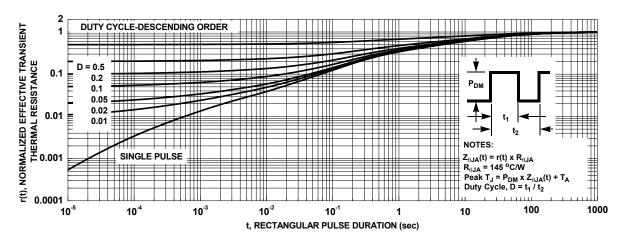
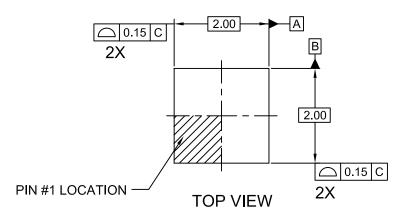
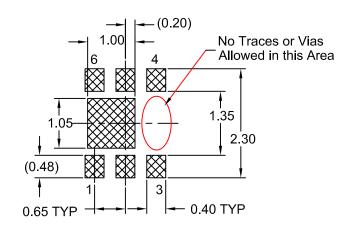
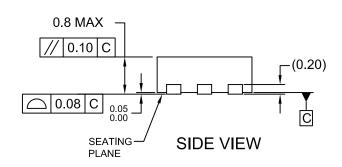


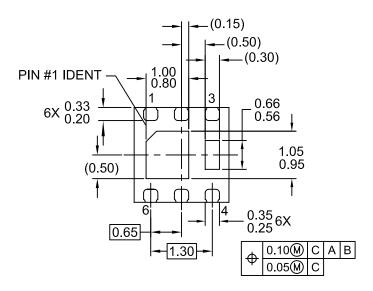
Figure 11. Junction-to-Ambient Transient Thermal Response Curve

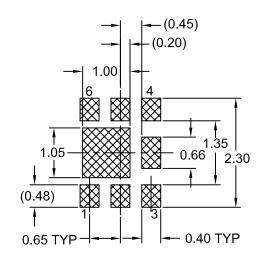




RECOMMENDED LAND PATTERN OPT 1







RECOMMENDED LAND PATTERN OPT 2

NOTES:

A. DOES NOT FULLY CONFORM TO JEDEC REGISTRATION MO-229 DATED AUG/2003

BOTTOM VIEW

- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994
- D. DRAWING FILENAME: MKT-MLP06Prev1.

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